

**METHOD OF FABRICATING AN INTEGRATED CIRCUIT THAT  
SEALS A MEMS DEVICE WITHIN A CAVITY**

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**ABSTRACT OF THE DISCLOSURE**

A method of fabricating an integrated circuit that includes a microelectromechanical (MEMS) device. The method includes forming a MEMS device on a substrate and forming an integrated circuit. The method further includes coupling the substrate to the integrated circuit to form a sealed cavity that includes the MEMS device. The substrate and the integrated circuit are coupled together in a controlled environment to establish a controlled environment within the cavity where the MEMS device is located.

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